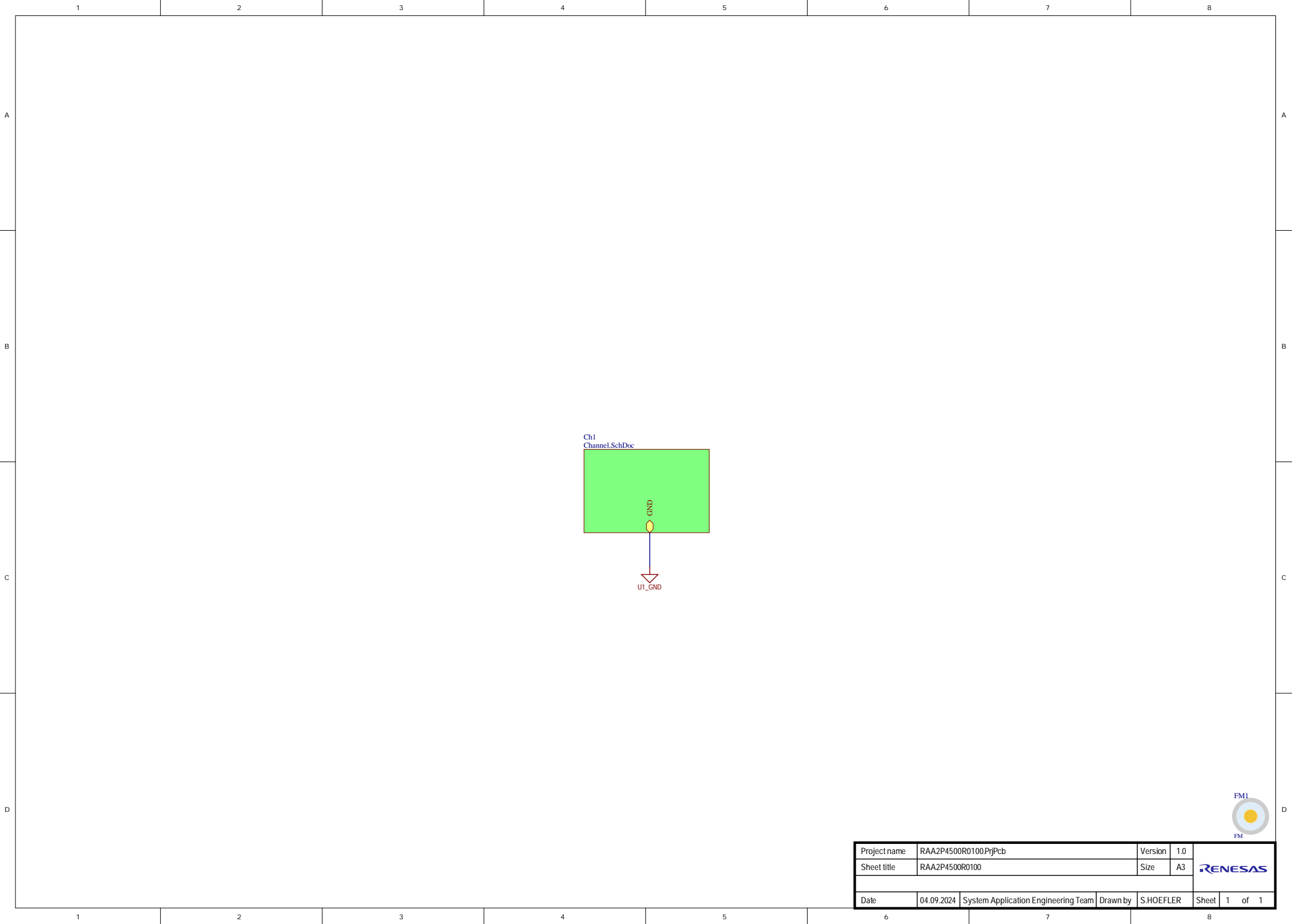


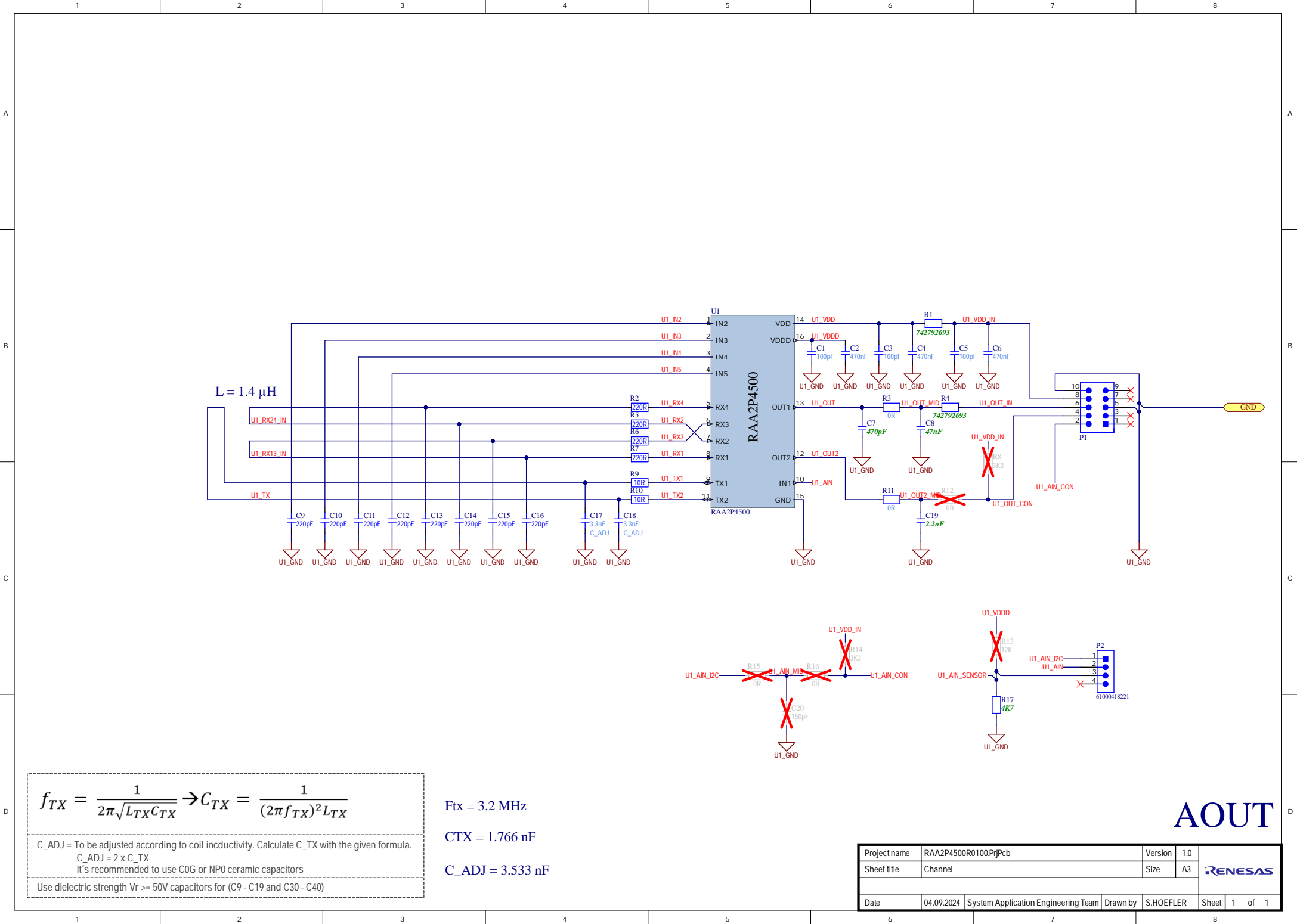


RAA2P4500R0100

Date:	04.09.2024
Project:	RAA2P4500R0100.PrjPcb
Version	1.0
Content:	Schematic Sensor PCB Layout Sensor PCB Placement Sensor PCB 3D Model PCB Manufacturing Requirements Sensor PCB Layer View Sensor PCB Layer Stack Bill Of Materials Target PCB Layout Target PCB 3D Model



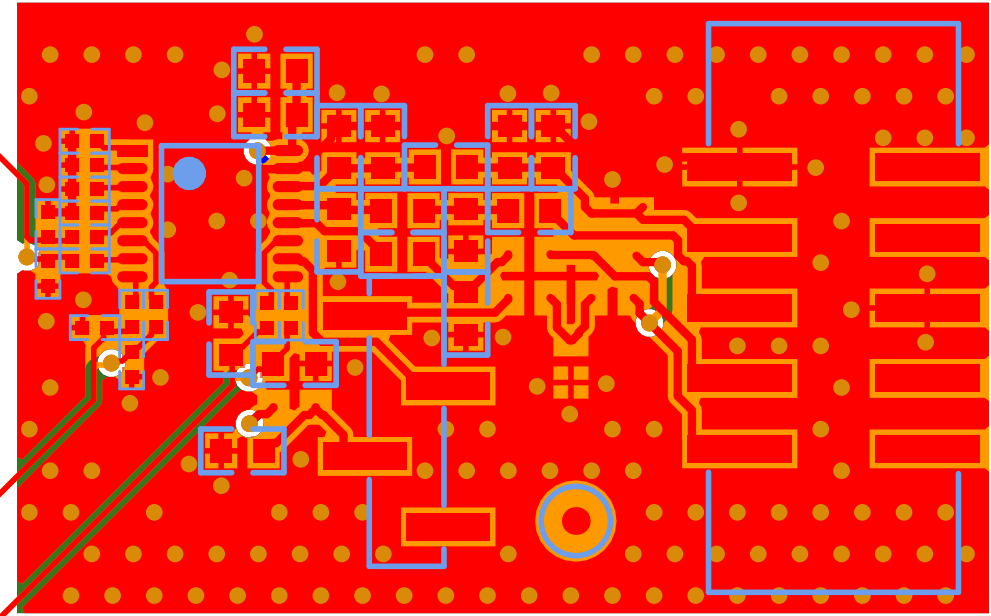
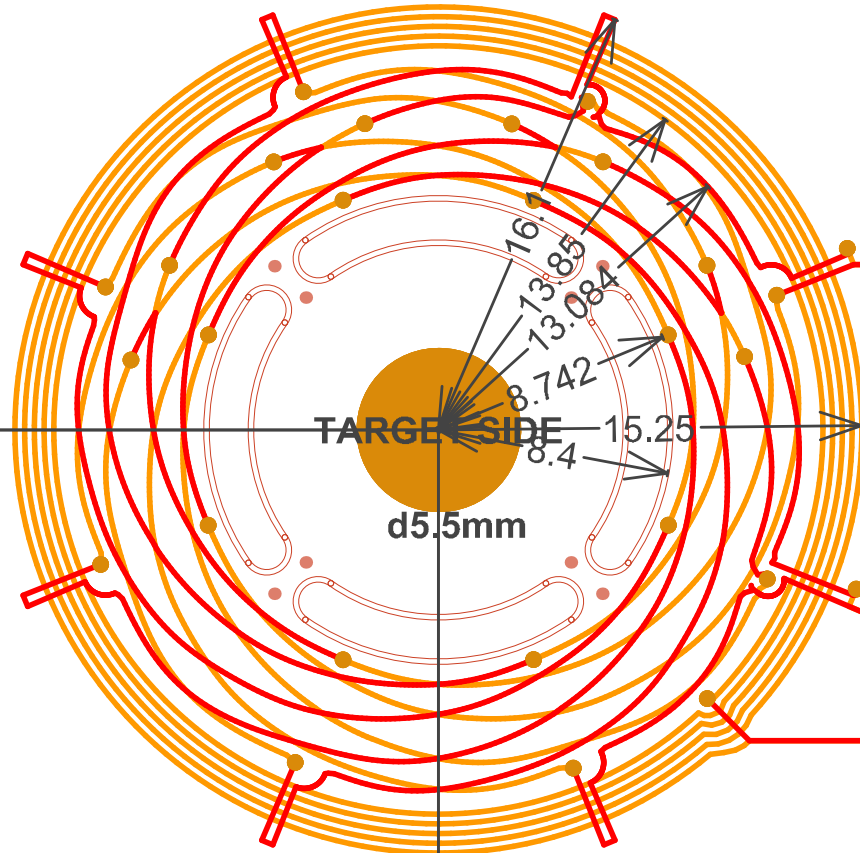
Project name	RAA2P4500R0100.PrfPcb			Version	1.0		
Sheet title	RAA2P4500R0100			Size	A3		
Date	04.09.2024	System Application Engineering Team		Drawn by	S.HOEFLER	Sheet	1 of 1



AOUT

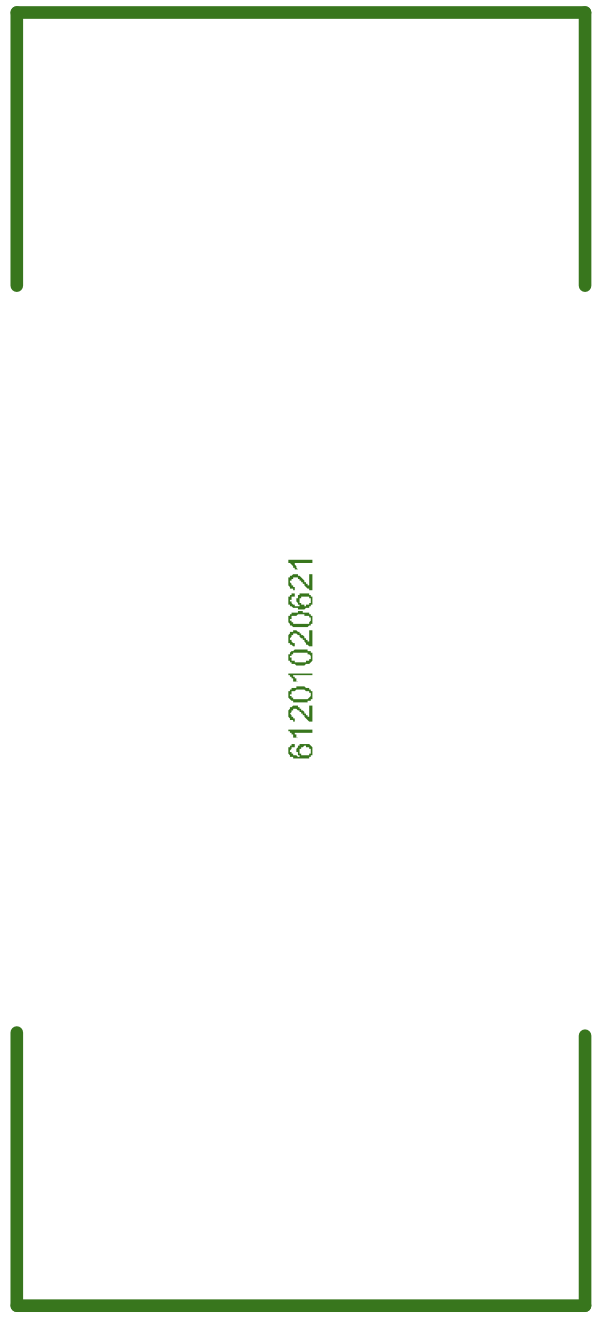
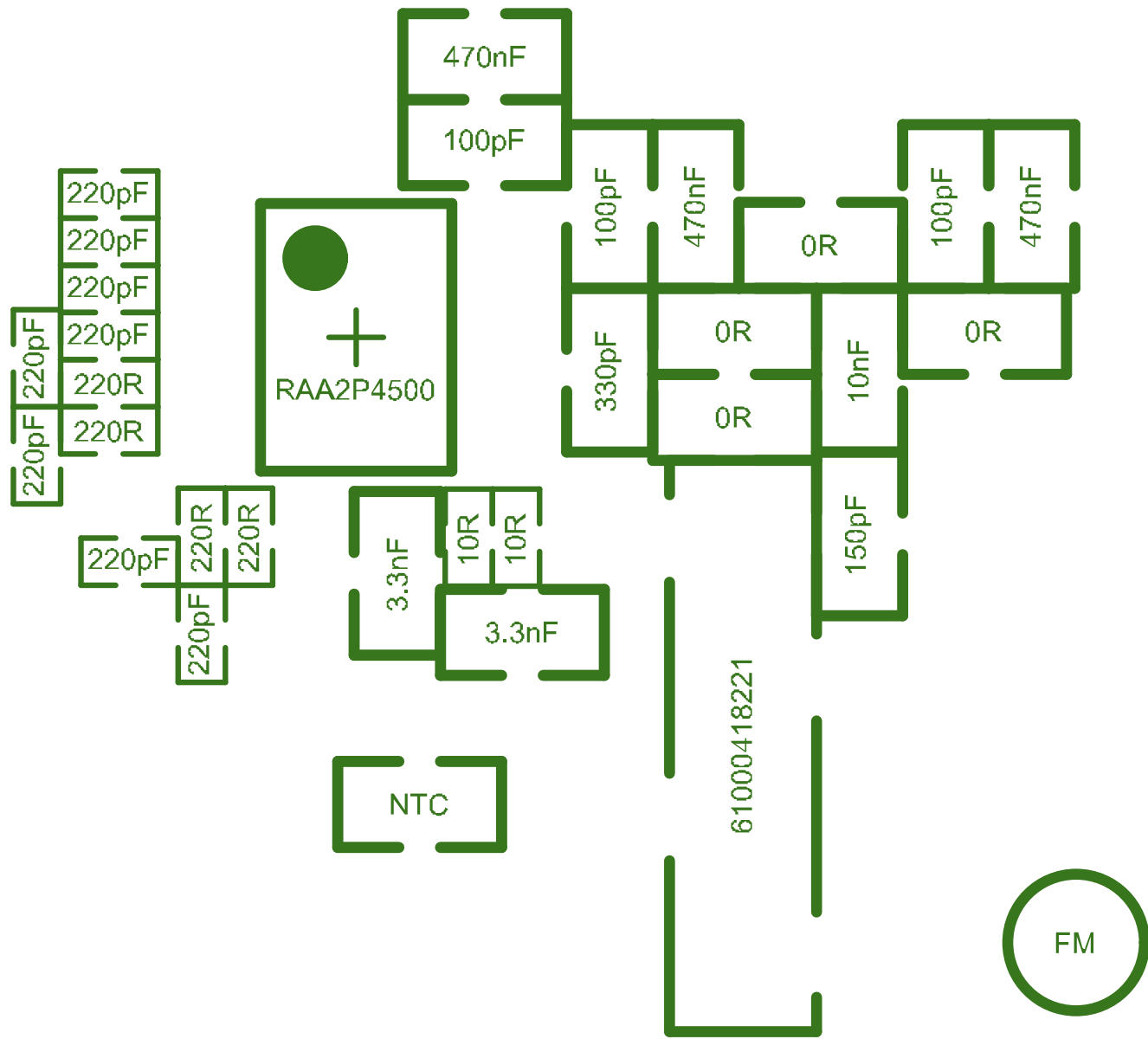
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Sheet title	Channel	Size	A3	
Date	04.09.2024	System Application Engineering Team	Drawn by	S.HOEFLER
Sheet	1	of	1	

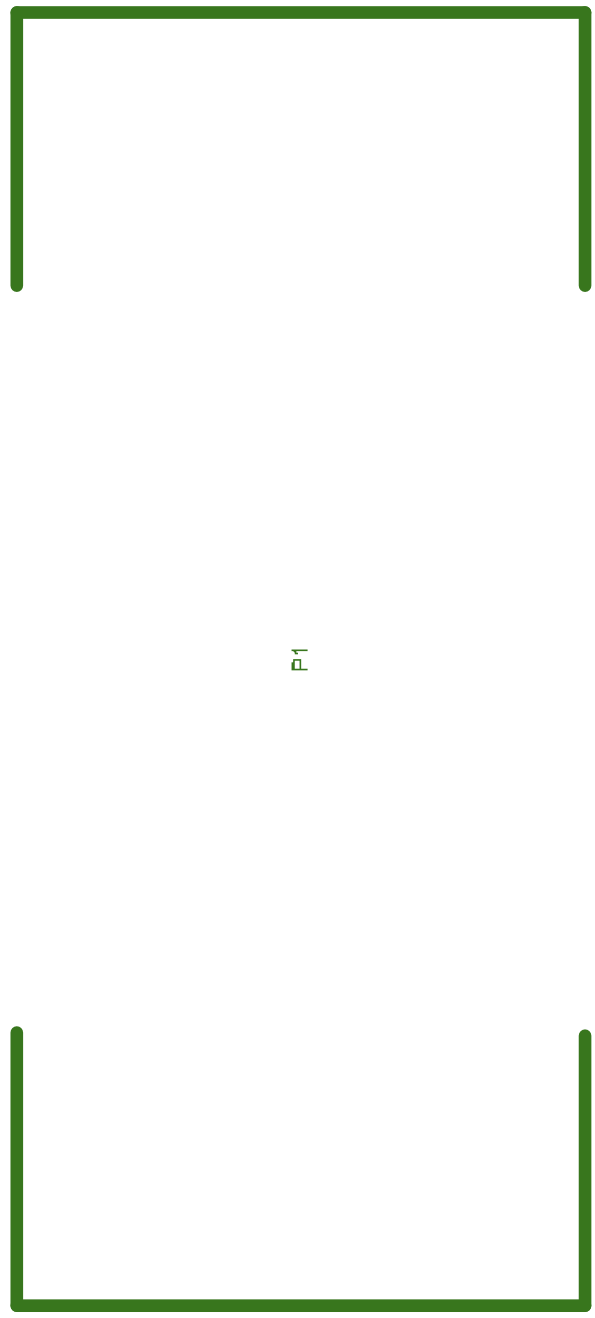
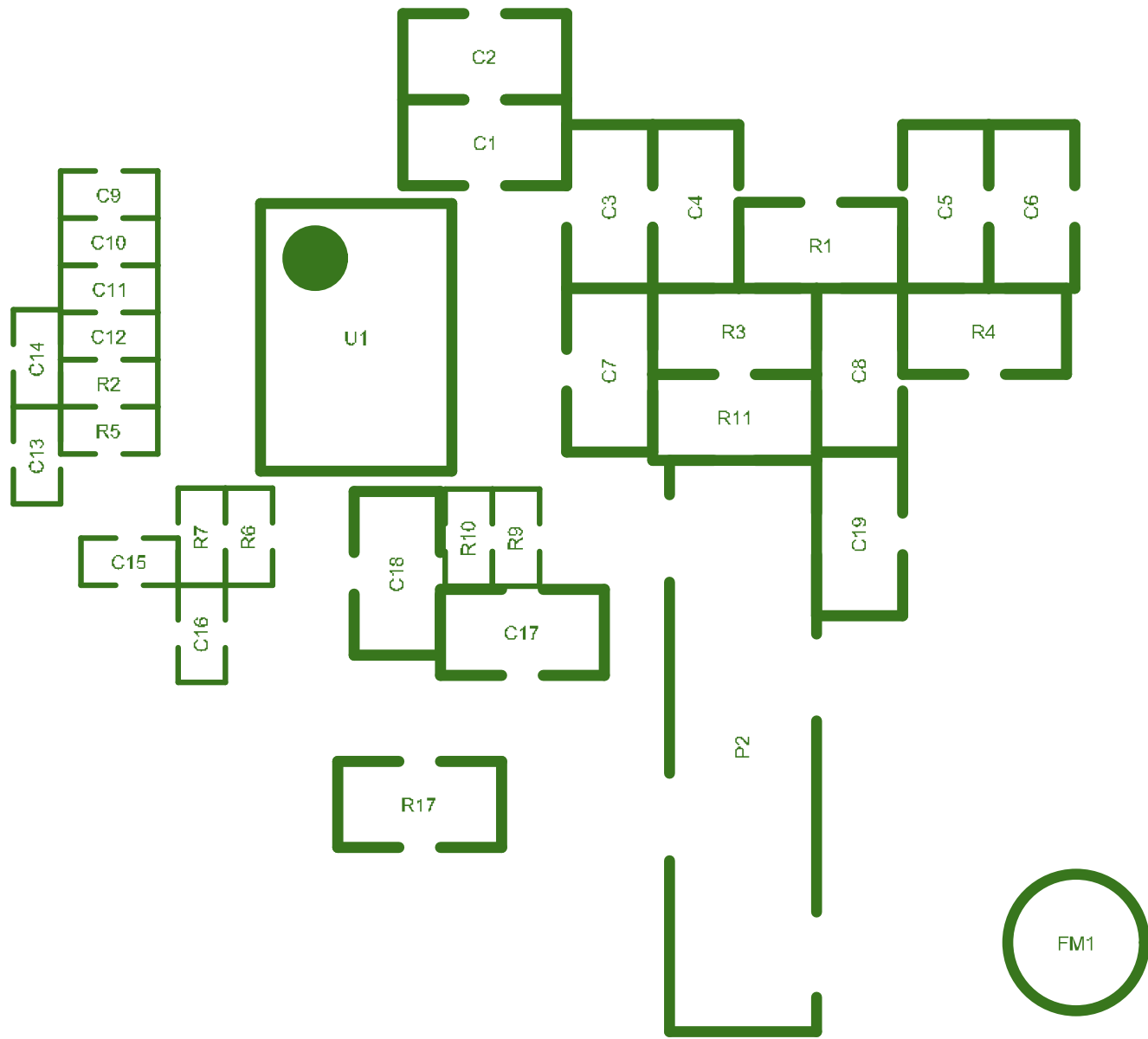
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RAA2P4500R0100

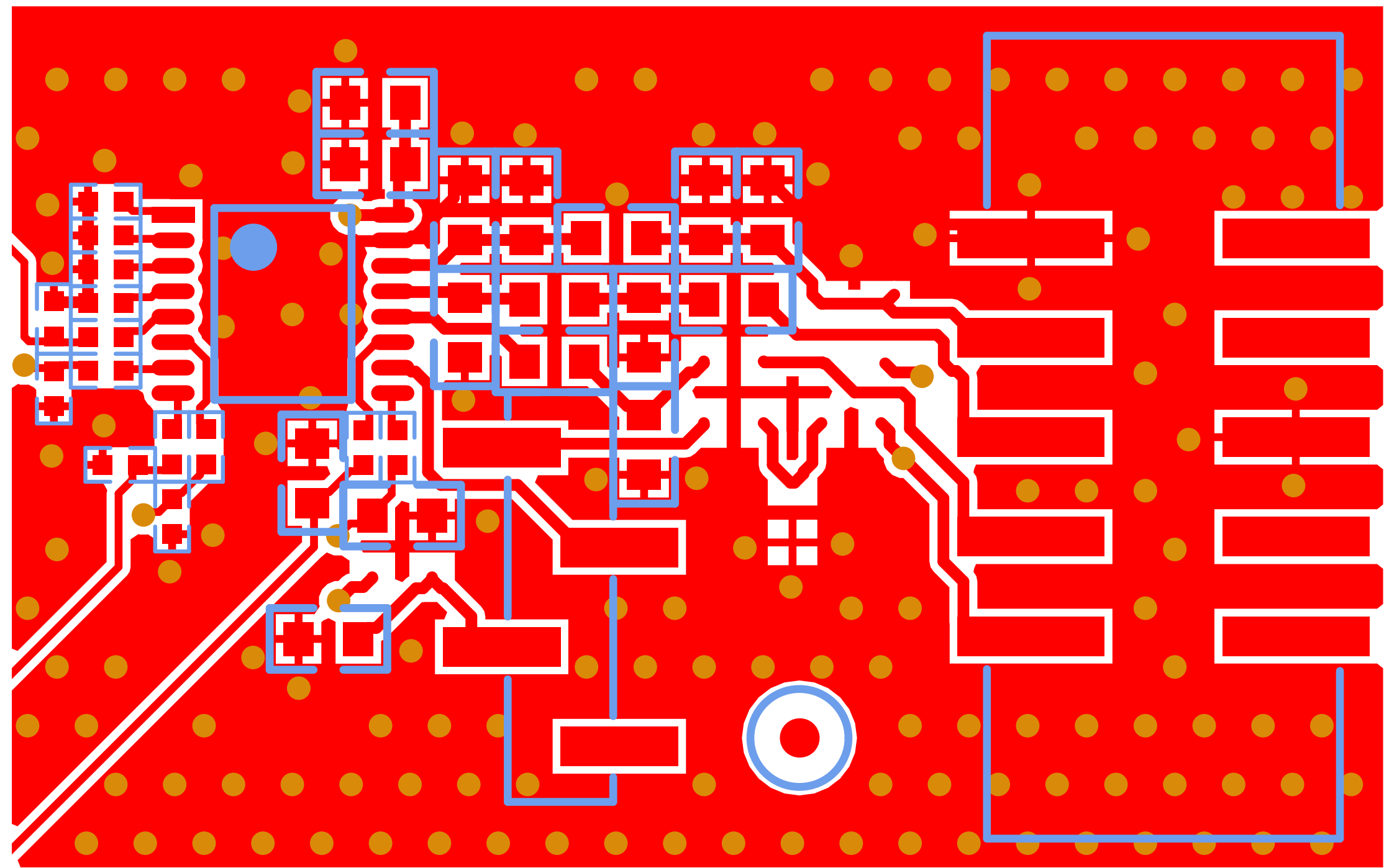
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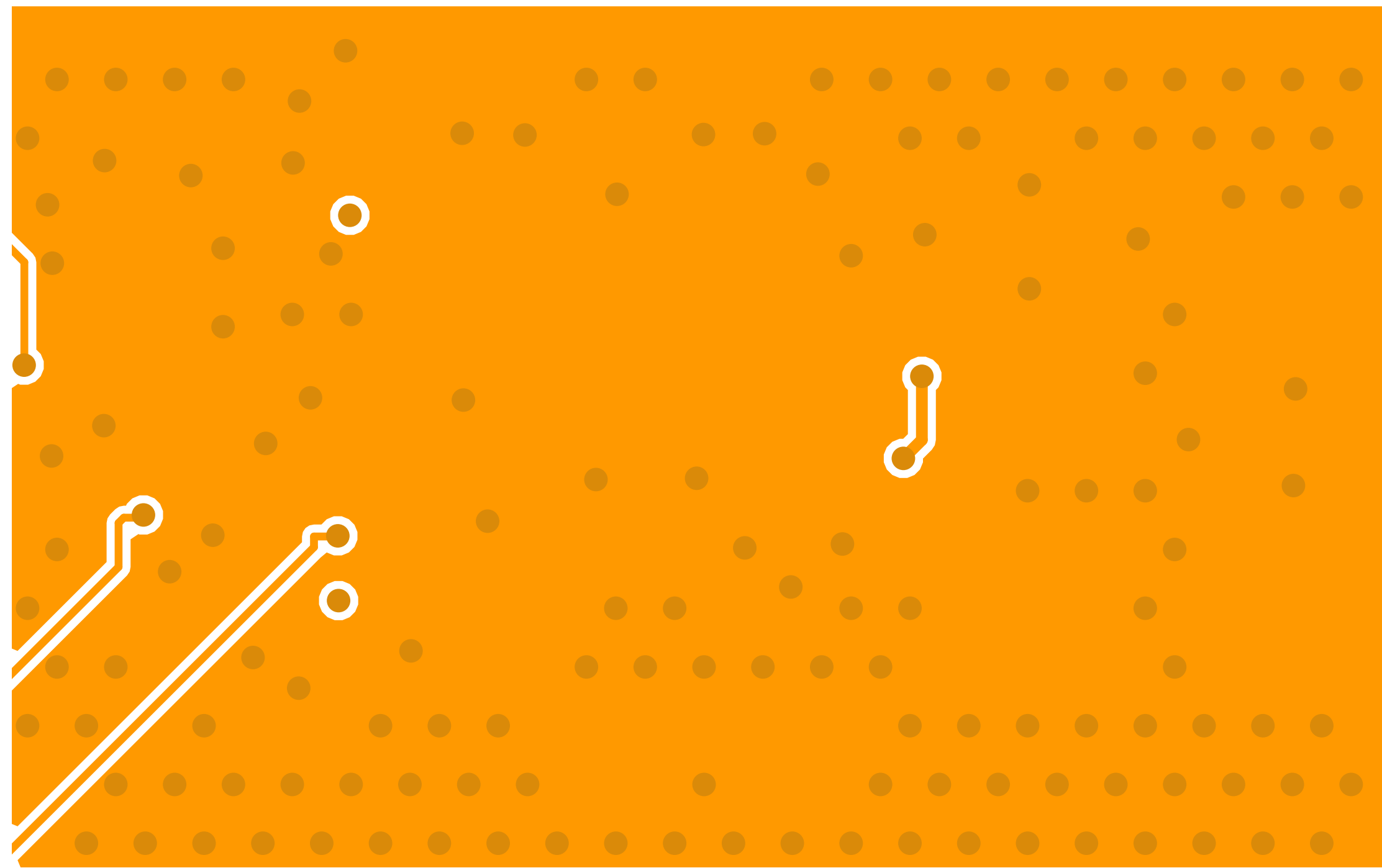


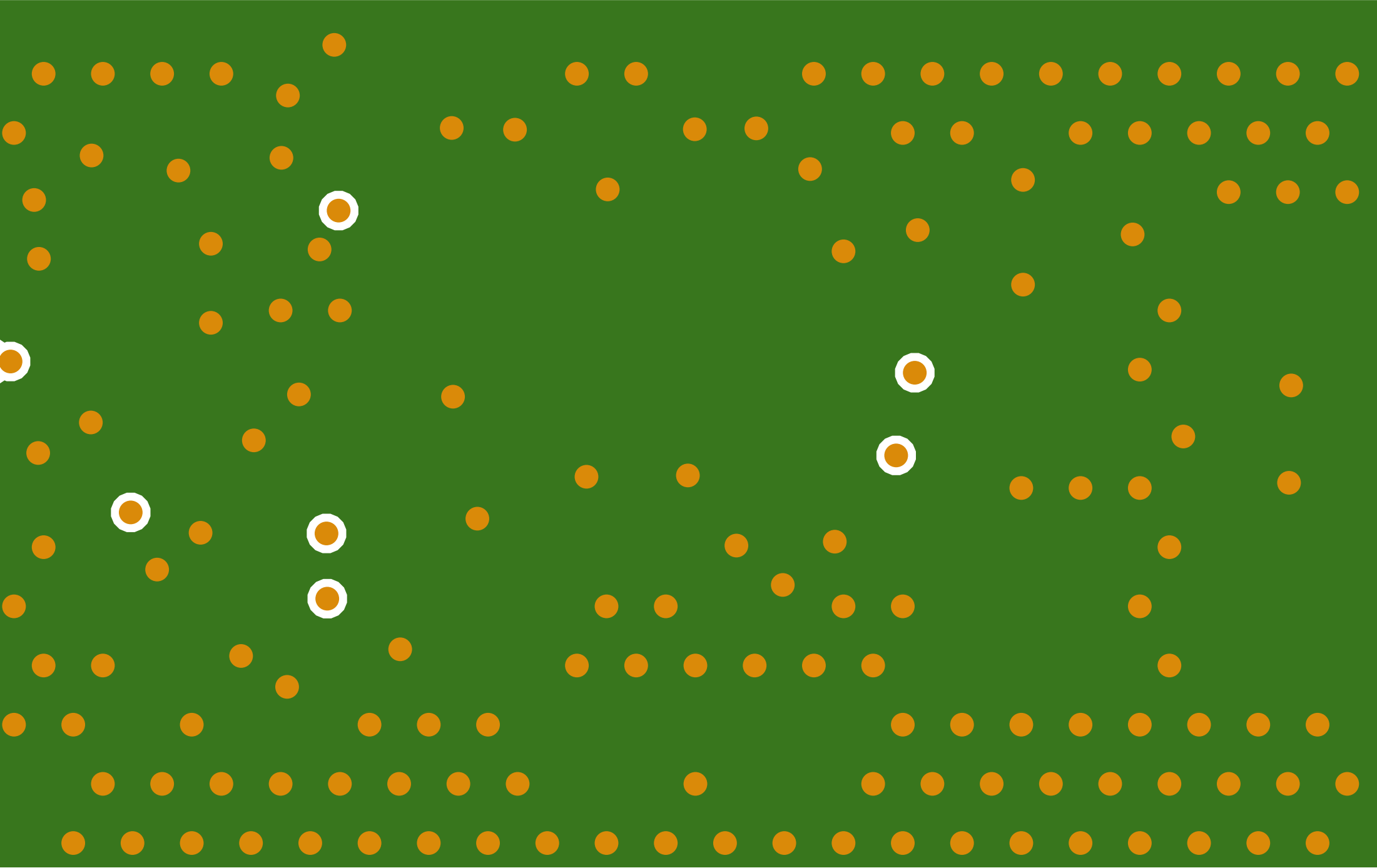


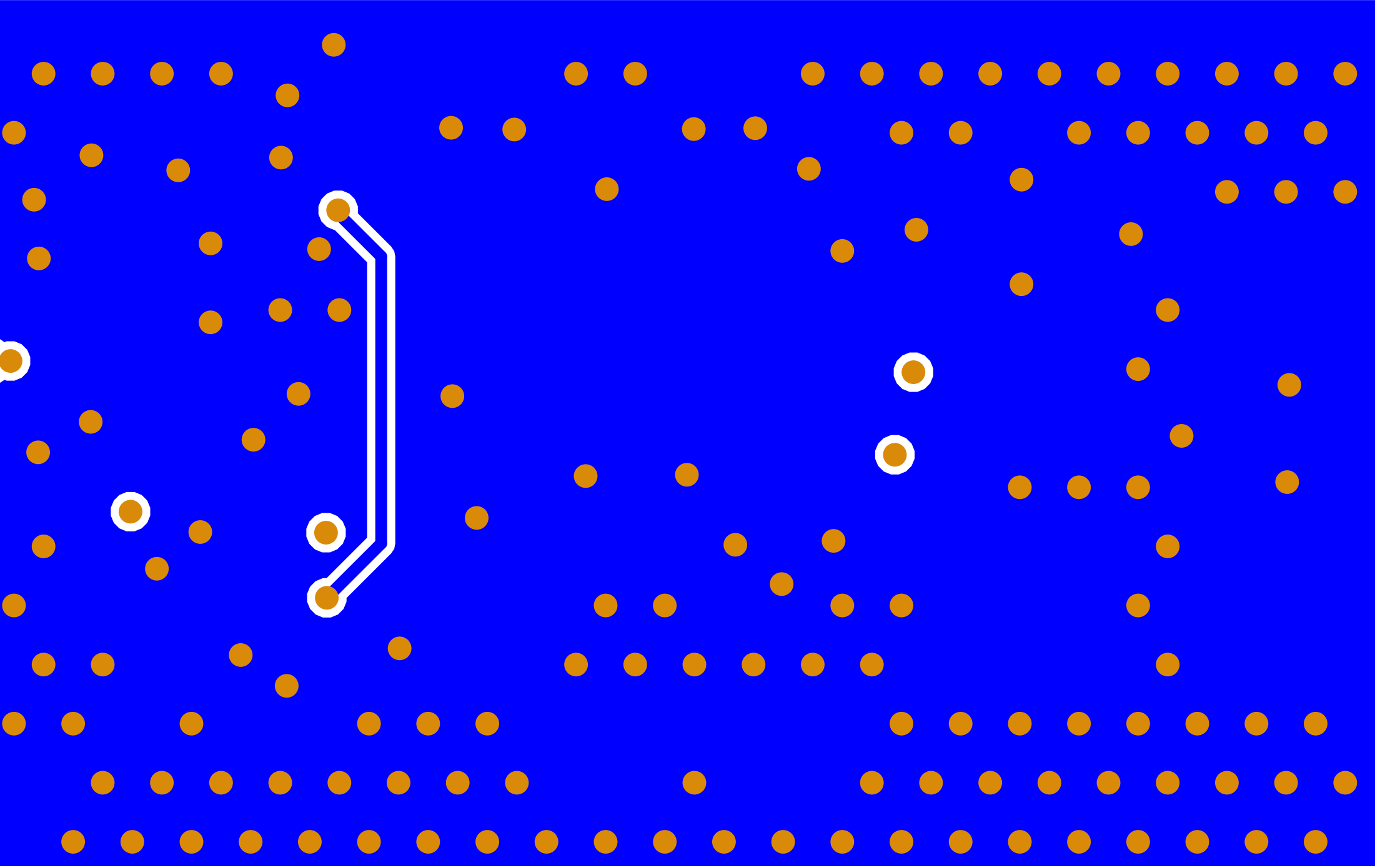
PCB Manufacturing requirements

Project Name	RAA2P4500R0100
Number of copper layers	4
PCB Base material	FR-4
Final PCB Thickness	1.6 mm (62.9 mil) \pm 10%
Thickness of copper coating	35um
Final cover	ENIG
Minimal copper width	0.2 mm (7.8 mil)
Minimal copper to copper distance	0.2 mm (7.8 mil)
Via hole/pad diameter	0.3 / 0.6 mm (11.8 / 23.6 mil)
Slotted holes	No
Panel size	74 x 40 mm (2913 x 1574 mil)
Silk screen color	White on TOP
Solder mask color	Blue
Blind Vias	No




















Board Stack Report

Stack Up		Layer Stack		
Layer	Board Layer Stack	Name	Material	Thickness
1		Top Overlay		0mm
2		Top Solder	Solder Resist	0.01mm
3		Top Layer		0.035mm
4		Dielectric 1	FR-4	0.32mm
5		Inner1		0.035mm
6		Dielectric2	FR-4	0.8mm
7		Inner2		0.035mm
8		Dielectric3	FR-4	0.32mm
9		Bottom Layer		0.035mm
10		Bottom Solder	Solder Resist	0.01mm
11		Bottom Overlay		0mm
	Height : 1.6mm			

Designator	Value	Quantity	Footprint	Description
C9, C10, C11, C12, C13, C14, C15, C16	220pF	8	C0402 3D	Capacitor 0402 220pF X7R
R1, R3, R4, R11	74279269 3, 0R	4	R0603 3D	Resistor 0603 0R
R2, R5, R6, R7	220R	4	R0402 3D	Resistor 0402 220R <5%
C1, C3, C5	100pF	3	C0603 3D	Capacitor 0603 100pF X7R
C2, C4, C6	470nF	3	C0603 3D	Capacitor 0603 470nF X7R
C17, C18	3.3nF	2	C0603 3D	Capacitor 0603 3.3nF NP0
R9, R10	10R	2	R0402 3D	Resistor 0402 10R <5%
C7	470pF	1	C0603 3D	Capacitor 0603 330pF X7R
C8	47nF	1	C0603 3D	Capacitor 0603 10nF X7R
C19	2.2nF	1	C0603 3D	Capacitor 0603 150pF X7R
P1		1	61201020621	WR-BHD Box Header, Male, pitch 2.54mm, SMT, Straight, 10p
P2		1	61000418221	WR-PHD Pin Header, SMT, pitch 2.54mm, Single Row, Vertical, 4p
R17	4K7	1	R0603 3D	NTCS0603E3103GLT NTC0603 10K

